



Serial No. : 2008-1555A

DATE : 2008/12/03

ITEM :

CRYSTAL OSCILLATORS

TYPE :

DSB321SDA

NOMINAL FREQUENCY :

26.000MHZ

SPEC No. :

1XTW26000CGA

Please acknowledge receipt of this specification by signing and returning a copy to us.

RECEIPT

DATE

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(signature)

(name)

General Manufacturer of Quartz Devices

**DAISHINKU CORP.**

1389 Shinzaike, Hiraoka-cho, Kakogawa, Hyogo  
675-0194 Japan  
Phone (81)79-425-3141 Fax (81)79-425-1134  
[http://www.kds.info/index\\_en.htm](http://www.kds.info/index_en.htm)

C.ENG.

*M. Yamashita*

ENG.

*H. Takase*

1. Device Name TCXO
2. Model Name DSB321SDA
3. Nominal Frequency 26.000 MHz
4. Mass 0.03g max.
5. Absolute Maximum Ratings

	Item	Symbol	Rating	unit
1	Supply Voltage	V <sub>CC</sub>	-0.3 ~ +6.0	V
2	Storage Temperature Range	T <sub>STG</sub>	-40 ~ +85	°C

## 6. Recommended Operating Conditions

	Item	Symbol	min.	typ.	max.	unit
1	Supply Voltage	V <sub>CC</sub>	+1.7	-	+3.6	V
2	Load Impedance (resistance part) (parallel capacitance)	L <sub>oad_R</sub>	9	10	11	kΩ
		L <sub>oad_C</sub>	9	10	11	pF
3	Operating Temperature Range	T <sub>OPR</sub>	-30	-	+85	°C

## 7. Electrical Characteristics

(T<sub>A</sub> = -30 ~ +85 °C, L<sub>OAD\_R</sub>//C = 10kΩ//10pF, V<sub>CC</sub>=+1.8V, 2.8V, 3.0V, 3.3V)

	Item	Conditions	Limits			unit	Notes
			min.	typ	max.		
1	Current Consumption		-	-	1.5	mA	
2	Output Level		0.8	-	-	V <sub>P-P</sub>	1
3	Symmetry	GND level (DC cut)	40/60	-	60/40	%	
4	Harmonics		-	-	-5	dBc	
5	Frequency Stability						
	1. Tolerance	After 2 times reflow	-	-	±1.5	ppm	2,3
	2. vs Temperature	T <sub>A</sub> = -30 ~ +85 °C	-	-	±0.5	ppm	4
	3. vs Supply Voltage	V <sub>CC</sub> =(+1.8V~3.3V)±5%	-	-	±0.2	ppm	
	4. vs Load Variation	L <sub>oad_R</sub> //C = (10kΩ//10pF) ±10%	-	-	±0.2	ppm	
	5. vs Aging	T <sub>A</sub> = Room ambient	-	-	±1.0	ppm/year	
6	Start Up	@90% of final Vout level	-	-	2.0	ms	
7	SSB Phase Noise	Relative to f0 level Offset 1kHz	-	-	-130	dBc/Hz	

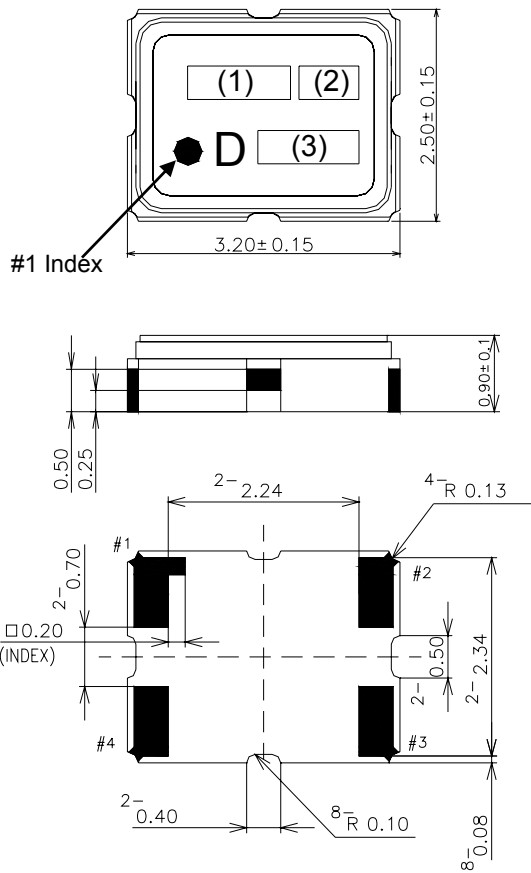
## Notes

1. Clipped sine wave (DC-coupled)
2. Ref. to Nominal Frequency.
3. Please leave after reflow in 2h or more at room ambient.
4. Ref. to Frequency. (T<sub>A</sub>=+25°C)

TITLE TCXO SPECIFICATION	Remark		
Date 2008/11/18	Spec. No. 1XTW26000CGA	Rev. A	Page 1/13

### 8. Outline, Pin Connections

#### Outline



#### Pin Connections

Pin No.	Connection
#1	GND
#2	GND
#3	Output
#4	V <sub>CC</sub>

#### Marking

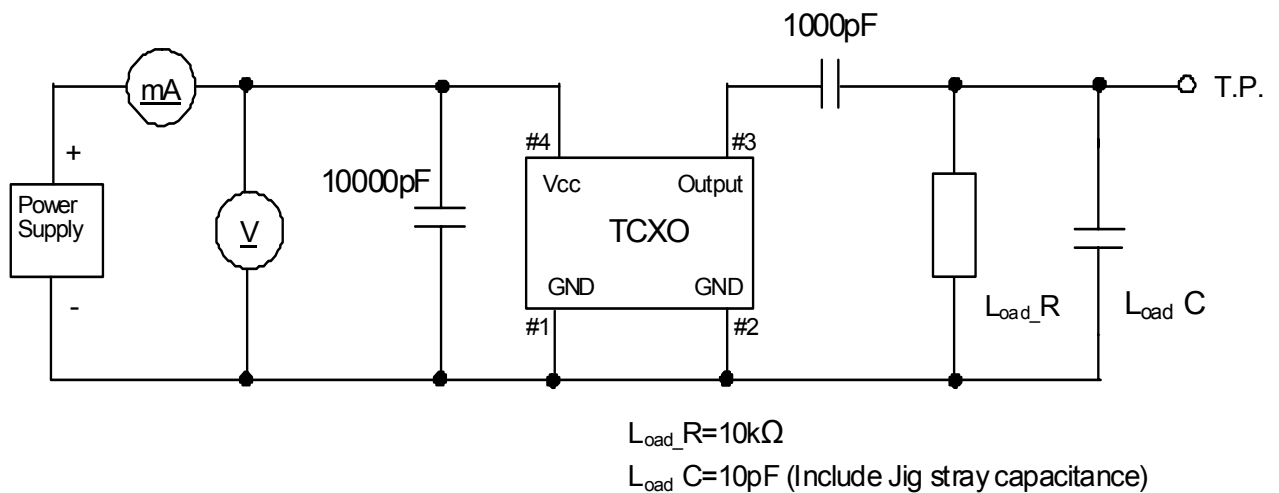
- (1) Frequency 26.00 (MHz, 4digits)
- (2) Model code T
- (3)EIA Date code Year (1digit) +Week (2digits)  
e.g. 2008/1/1 → 801

unit: mm

Dimensional Tolerance: ±0.15

(Unless otherwise noted)

### 9. Measurement Circuit



TITLE TCXO SPECIFICATION		Remark		
Date 2008/11/18	Spec. No. 1XTW26000CGA	Rev. A	Page 2/13	

## 10. Mechanical Characteristics

All test is performed after 3-times reflow (Clause.13) except 10.10 (Resistance to soldering heat)

	Test Item	Test Description	Requirements
1	Drop	Natural drop (on concrete) Mounting on the set or test fixture.(Total weight 100g) Height : 150cm Direction : X,Y,Z, 6directions Test cycle : 3cycles Reference specification : EIAJ-ED-4702A Method5	df/f=<±1.0ppm
2	Vibration	Sweep range : 10Hz~500Hz Sweep speed : 11min./cycle Amplitude : 1.5mm (10~55Hz) Acceleration : 200m/s <sup>2</sup> (55~500Hz) Direction : X,Y,Z, 3directions Test cycle : 10cycles Reference specification : IEC 60068-2-6	df/f=<±0.5ppm
3	Shock	Acceleration : 100G (1000m/s <sup>2</sup> ) Direction : X,Y,Z, 6directions Duration : 6ms Test cycle : 3times/each directions Reference specification : IEC 60068-2-27	df/f=<±0.5ppm
4	PCB bend strength	PWB : t=1.6mm Pressure speed : 1.0mm/s Bend width : 1→2→3mm Duration : 10±1s Reference specification : IEC 60068-2-21 Ue1	df/f=<±0.5ppm No visible damage.
5	Adherence nature	PWB : t=1.6mm Pressure : 10N Duration : 10±1s Direction : X,Y, 2directions Reference specification : IEC 60068-2-21 Ue3	df/f=<±0.5ppm No visible damage.
6	Package strength	Pressure : 10N Duration : 10±1s Reference specification : IEC 60068-2-77	df/f=<±0.5ppm No mechanical damage. No leak damage.
7	Gross leak	It is immersed for 3 min into +125±5°C Chlorofluorocarbon (CFCs) liquid. Reference specification : IEC 60068-2-17	No continuous air bubbles.
8	Fine leak	It shall be measured by the helium leak detector after pressurization for 60 min by the pressure of (3.92±0.49) x10 <sup>5</sup> Pa in a helium gas atmosphere. Reference specification : IEC 60068-2-17	Less than 1.0x10 <sup>-9</sup> Pa m <sup>3</sup> /s.
9	Solderability	Solder bath method (Flow soldering) Soldering temperature : +245±5°C Duration : 3±0.3s Reference specification : IEC 60068-2-58	A new uniform coating of solder shall cover a minimum of 95% of the surface being immersed.
10	Resistance to soldering heat	Solder iron method Bit temperature : +350±10°C Duration : 3+1/-0s /each terminal Reference specification : IEC 60068-2-20	df/f=<±0.5ppm dVout=<±0.2Vp-p No visible damage.
		Reflow In refer to temperature profile shown in clause 13. Test cycle : 3cycles It shall be measured after 2h at room temperature, humidity. Reference specification : IEC 60068-2-58	df/f=<±1.0ppm dVout=<±0.2Vp-p No visible damage.

TITLE  
TCXO SPECIFICATION

Remark

Date  
2008/11/18Spec. No.  
1XTW26000CGARev.  
APage  
3/13

## 11. Environmental Characteristics

All test is performed after 3-times reflow (Clause.13)

	Test Item	Test Description	Requirements
1	Low temperature storage	Temperature : $-40\pm 3^{\circ}\text{C}$ Duration : 1000h It shall be measured after 2h at room temperature, humidity. Reference specification : IEC 60068-2-1 Ab	$df/f < \pm 1.0\text{ppm}$ $dV_{out} < \pm 0.2\text{Vp-p}$
2	High temperature storage	Temperature : $+85\pm 2^{\circ}\text{C}$ Duration : 1000h It shall be measured after 2h at room temperature, humidity. Reference specification : IEC 60068-2-2 Bb	$df/f < \pm 1.0\text{ppm}$ $dV_{out} < \pm 0.2\text{Vp-p}$
3	Humidity	Temperature : $+85\pm 2^{\circ}\text{C}$ R.H. $85\pm 5\%$ Duration : 1000h It shall be measured after 2h at room temperature, humidity. Reference specification : IEC 60068-2-3	$df/f < \pm 1.0\text{ppm}$ $dV_{out} < \pm 0.2\text{Vp-p}$
4	HTB	Temperature : $+85\pm 2^{\circ}\text{C}$ Duration : 1000h BIAS : Max value of supply voltage It shall be measured after 2h at room temperature, humidity. Reference specification : IEC 60068-2-2 Bb	$df/f < \pm 1.0\text{ppm}$ $dV_{out} < \pm 0.2\text{Vp-p}$
5	THB	Temperature : $+40\pm 2^{\circ}\text{C}$ R.H. 90~95% Duration : 1000h BIAS : Max value of supply voltage It shall be measured after 2h at room temperature, humidity. Reference specification : IEC 60068-2-3	$df/f < \pm 1.0\text{ppm}$ $dV_{out} < \pm 0.2\text{Vp-p}$
6	Thermal shock	200 cycles of Temperature: $-40\pm 3^{\circ}\text{C}:0.5\text{h} \rightarrow +85\pm 2^{\circ}\text{C}:0.5\text{h}$ It shall be measured after 2h at room temperature, humidity. Reference specification : IEC pub.68-2-14.Na	$df/f < \pm 1.0\text{ppm}$ $dV_{out} < \pm 0.2\text{Vp-p}$ Any cracks shall not appear.
7	ESD	Model : Machine Model (MM) $V_s = \pm 200\text{V}$ ( $C_1 = 200\text{pF}$ , $R_2 = 0\Omega$ ) Number of times : 3times Each terminals except common terminal. (Connect to test terminal) Reference specification : EIA/JESD22-A114	$df/f < \pm 1.0\text{ppm}$ No visible damage.
		Model : Human Body Model (HBM) $V_s = \pm 1500\text{V}$ ( $C_1 = 100\text{pF}$ , $R_2 = 1500\Omega$ ) Number of times : 3times Each terminals except common terminal. (Connect to test terminal) Reference specification : EIA/JESD22-A115	$df/f < \pm 1.0\text{ppm}$ No visible damage.

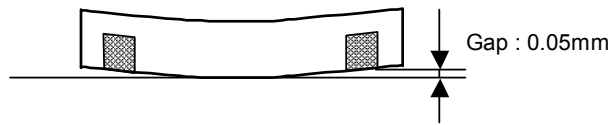
TITLE  
TCXO SPECIFICATION

Remark

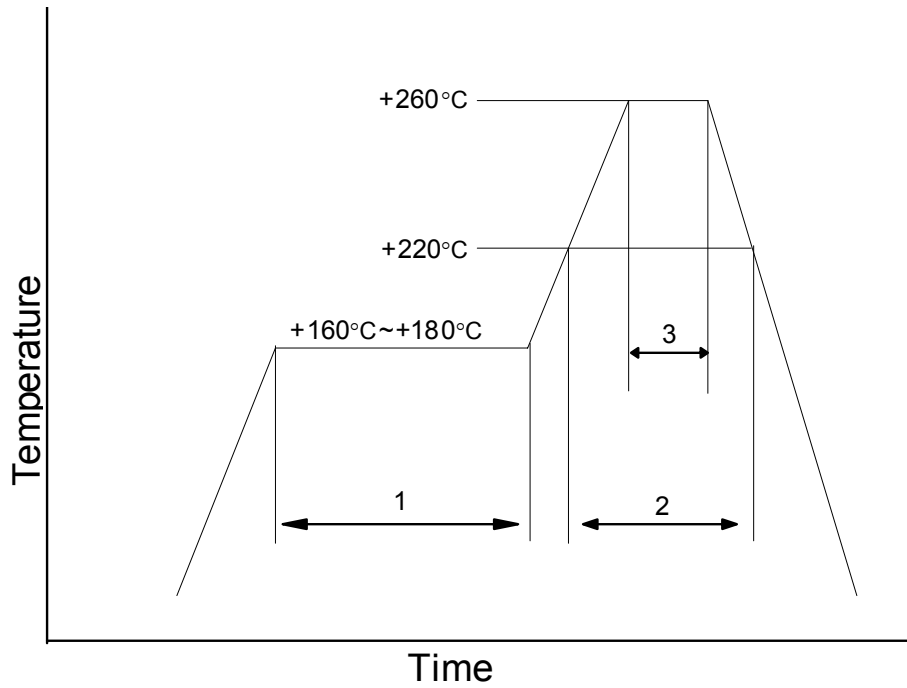
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1XTW26000CGARev.  
APage  
4/13

12. Flatness of Terminal

When the component is placed on the flat surface, the gap from the connecting terminal shall not exceed 0.05 mm.



13. Reflow Profile



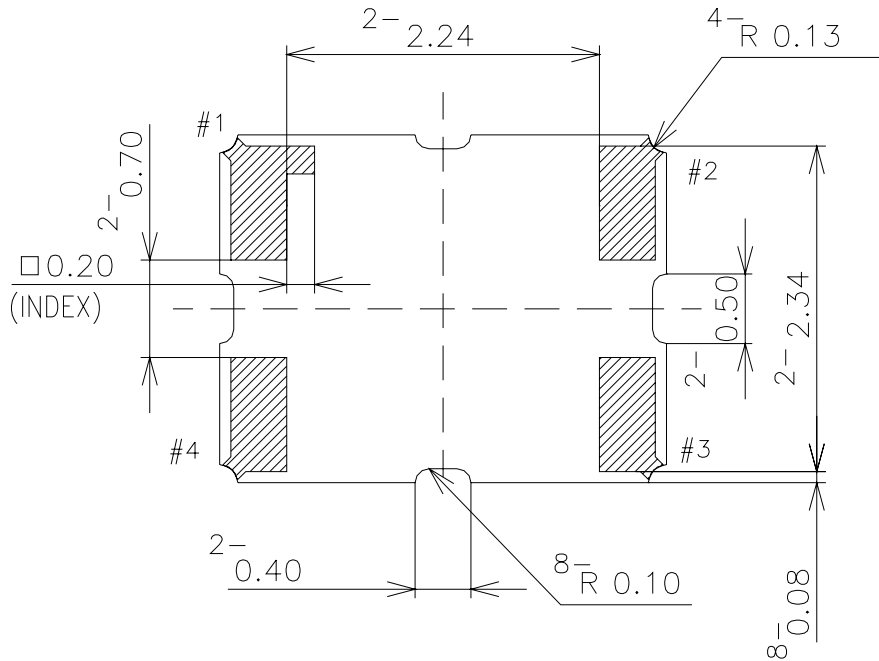
1	Preheat	+160~+180°C	120s
2	Primary Heat	+220°C	60s
3	Peak	+260°C	10s max.

TITLE TCXO SPECIFICATION		Remark		
Date 2008/11/18	Spec. No. 1XTW26000CGA	Rev. A	Page 5/13	

14. Bottom View / Land Pattern Layout / Metal Mask Hole

(1) Bottom View

A through hole is not located on the bottom (mounting side).



**BOTTOM VIEW**

unit : mm

Dimensional Tolerance: ±0.15mm

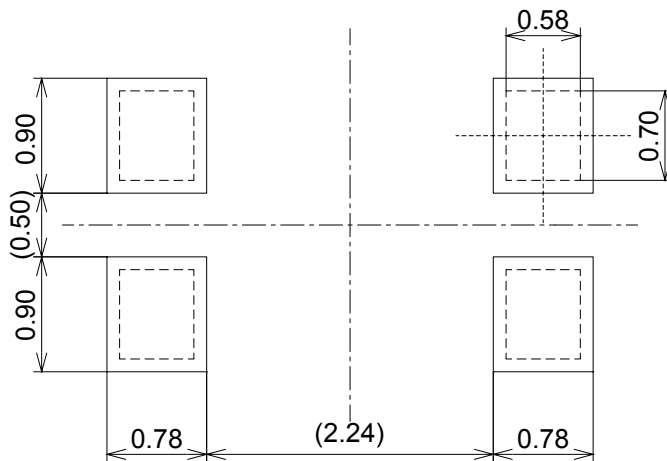


Mounting terminal

(2) Land Pattern Layout / Metal Mask Hole

The following land pattern is reference design. The electrical characteristic clause7 shall be satisfied with mounting to this land. The land pattern can be changed in the limits to which a test land and a mounting land are not connected. And it does not any effect to the electrical characteristics.

Mask thickness recommends 0.12mm.



**TOP VIEW**

unit : mm

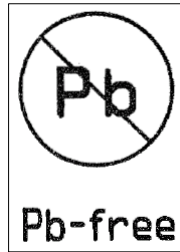
—— Land Pattern  
 - - - - Metal Mask Hole

TITLE TCXO SPECIFICATION		Remark		
Date 2008/11/18	Spec. No. 1XTW26000CGA	Rev. A	Page 6/13	

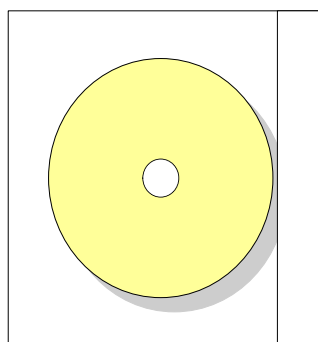
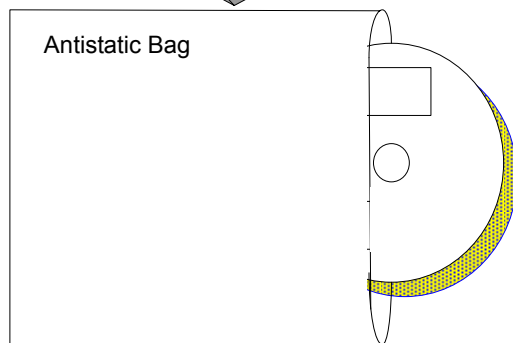
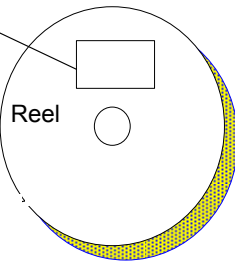




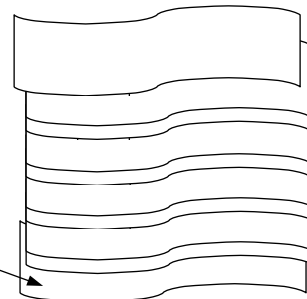
Pb-free Label



Lot Label

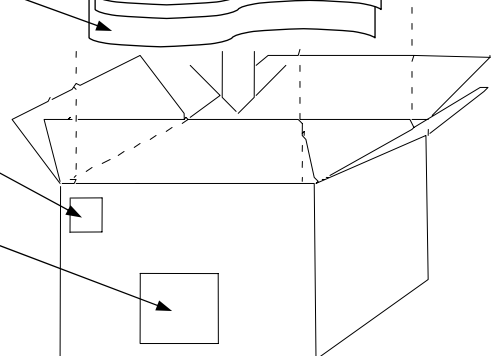


Air Cushion



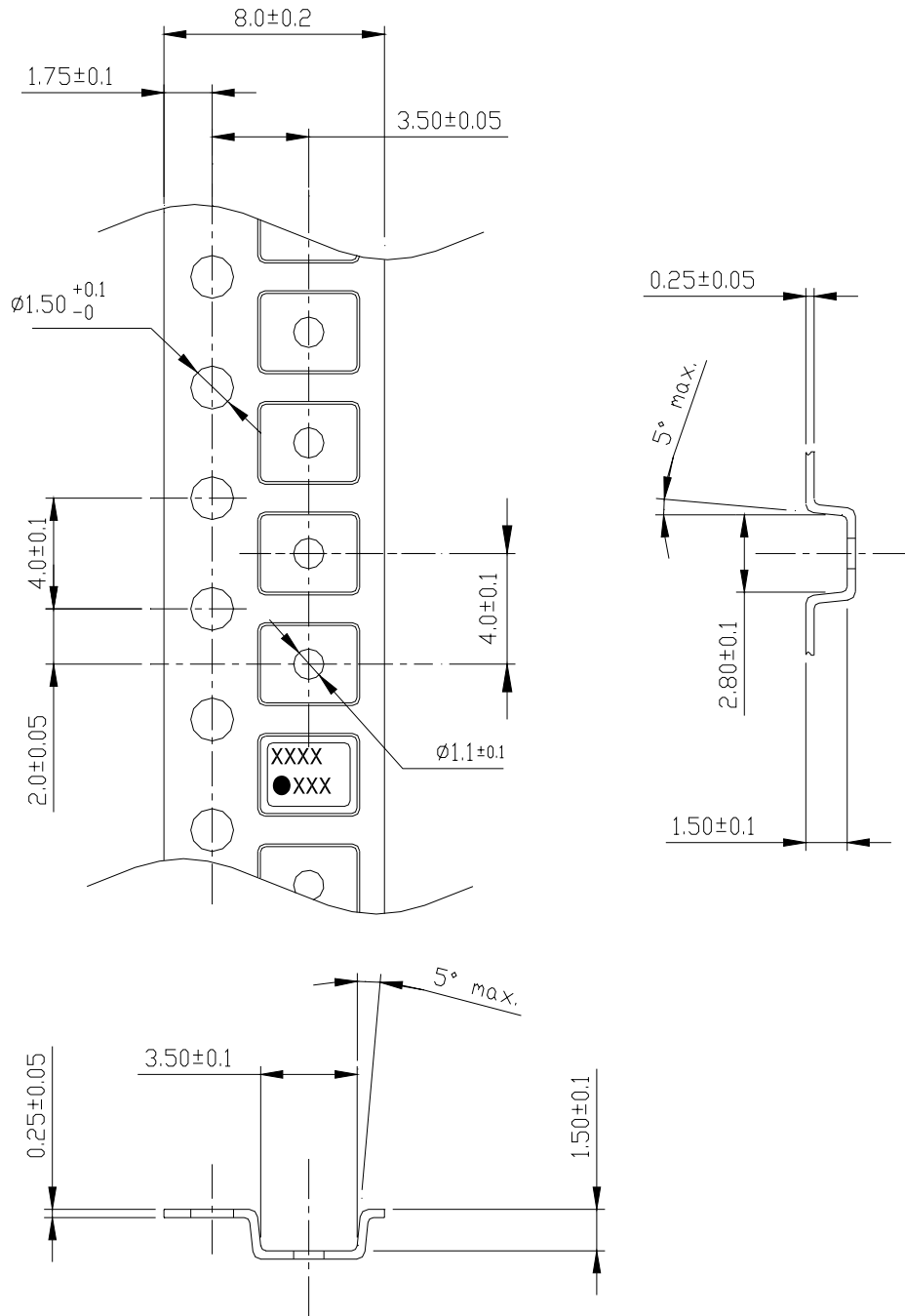
Pb-free Label

Shipping Label



The product is packed up with the method which does not break in the handling by a shipping agent.

TITLE TCXO SPECIFICATION		Remark	
Date 2008/11/18	Spec. No. 1XTW26000CGA	Rev. A	Page 8/13



1) Clearance of an embossing tape, and a product unit : mm

Direction	Pocket size	TCXO size	Clearance
L	3.5±0.1	3.2±0.15	0.3±0.25
W	2.8±0.1	2.5±0.15	0.3±0.25
H	1.5±0.1	1.0 max.	0.5 min.

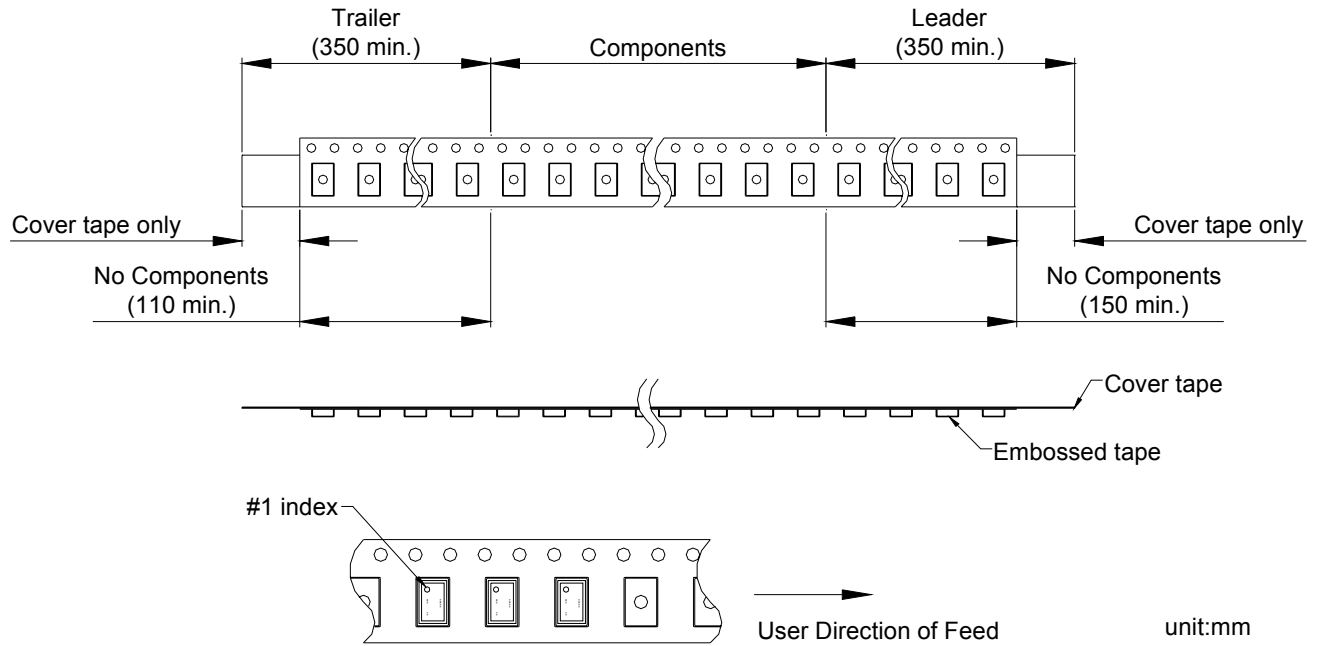
2) Quality : Polystyrene(Conductivity)

3) Tensile strength of an embossing tape : more than 14N

unit : mm

Fig.1. Embossed tape Format and Dimensions

TITLE TCXO SPECIFICATION		Remark	
Date 2008/11/18	Spec. No. 1XTW26000CGA	Rev. A	Page 9/13



Direction of taking up reel is clock-wise as above.

There are sprocket holes on the right hand side of the tape when it is pulled out as shown above.

**Peel strength**

Pulling angle 165 ~ 180°, pulling speed at 300mm/min, strength should be 0.2 ~ 0.7N.

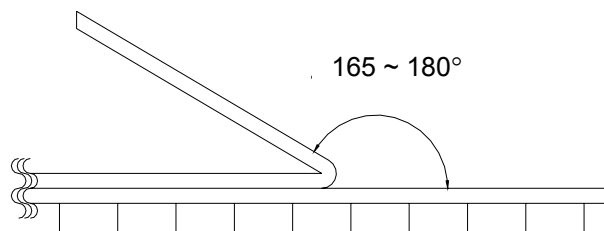
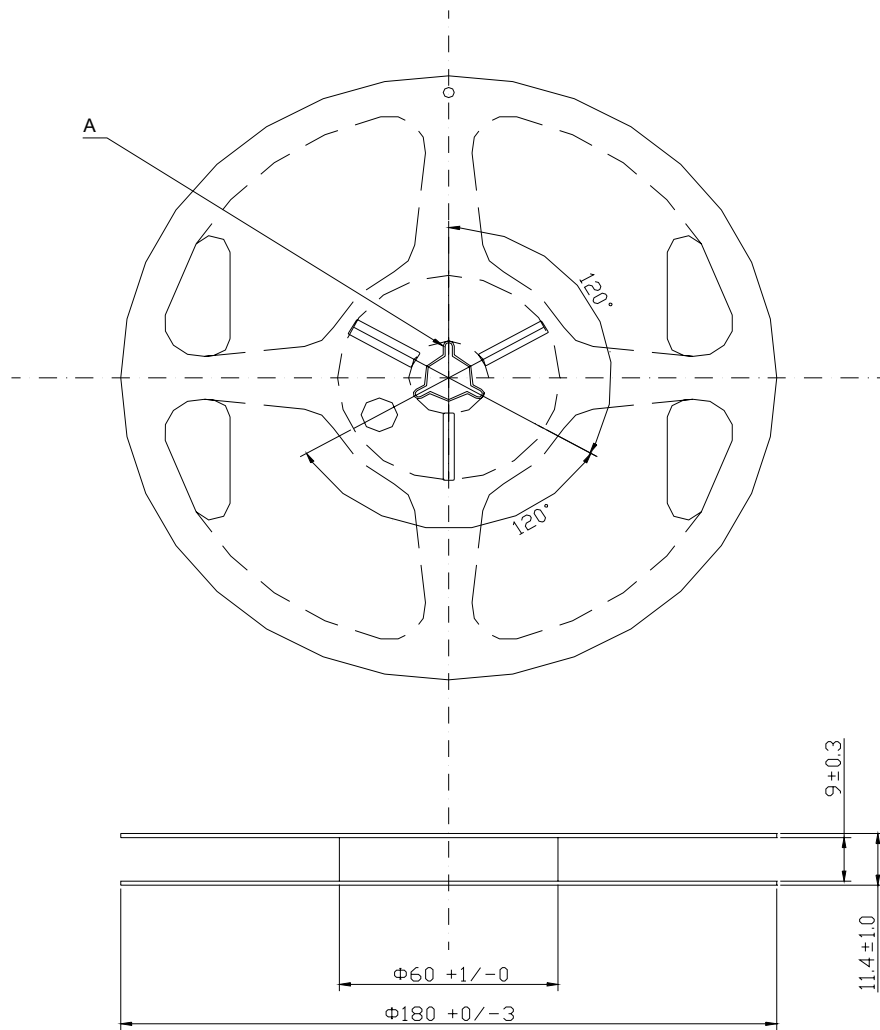


Fig.2. Taping Specification

TITLE TCXO SPECIFICATION		Remark	
Date 2008/11/18	Spec. No. 1XTW26000CGA	Rev. A	Page 10/13



Material:Polystyrene (Conductivity)  
unit:mm

Section A

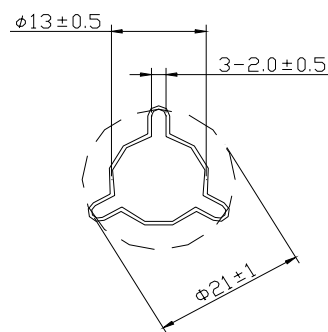


Fig.3. Reel Dimensions

<p>TITLE TCXO SPECIFICATION</p>	<p>Remark</p>		
<p>Date 2008/11/18</p>	<p>Spec. No. 1XTW26000CGA</p>	<p>Rev. A</p>	<p>Page 11/13</p>

**16. Notes on mounting and handling****16.1 Storage environment**

- (1) The temperature and humidity of a storage place, Please give +5~+40°C and 40~85% as a standard.
- (2) Please use this product within one year from the packing label date of issue.
- (3) Please avoid the place which generates corrosive gas, and the place with much dirt.
- (4) Please keep it in a place with little temperature change.

Dew condensation arises owing to a rapid temperature change and solderability becomes bad.

**16.2 Be cautions to static electricity and high voltage.**

**16.3** This product has sufficient durability to fall and vibration. However, conditions may change to the fall after mounting to a PWB, and vibration. When you should drop on a floor the PWB which mounted the product or too much shock is added. Please use after a performance check.

**16.4** Please check that the curvature of the substrate at the time of substrate cutting does not affect a product. Moreover, especially when a product is near the position of a PWB guide pin, and the position of a PWB break, be careful.

**16.5** The part concerned does not correspond to washing.

**16.6** Please repair at +260°C in 10s with hot air or +350°C in 5s with solder Iron.

**17. Mandatory control****17.1 Ozone-depleting substance**

It regulates by the U.S. air purifying method (November, 1990 establishment). ODS of CLASS-1 and CLASS-2 is not contained or used.

**17.2 PBDE, PBBs**

PBDE, PBBs are not contained into all the material currently used for this product.

**17.3 RoHS**

Following material restricted by RoHS is not included or used. Lead, mercury, cadmium, hexavalent , chromium ,PBB and PBDE.

**17.4 Law Concerning Examination and Regulation of Manufacture, etc. of Chemical Substances**

All the material currently used for this product is based on "Law Concerning Examination and Regulation of Manufacture, etc. of Chemical Substances". It is a registered material.

**17.5 Lead**

Leads, such as solder, are not used for this product.(Lead Free)

**17.6 About the existence of silver and mercury use**

The silver of very small quantity is contained in the conductive adhesives used for adhesion of Blank. Moreover, mercury is used. It does not get down.

**18. The country of origin / factory name / address**

Country of origin : Japan

Factory name : DAISHINKU Corp. Tottori Production Div.

Address : 7-3-21 Wakabadai minami, Tottori 689-1112

TITLE TCXO SPECIFICATION	Remark		
Date 2008/11/18	Spec. No. 1XTW26000CGA	Rev. A	Page 12/13



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